



MOSFETs Silicon 430V N-Channel MOS

■ Applications

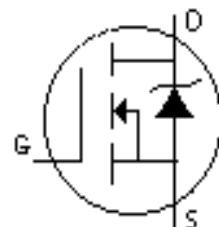
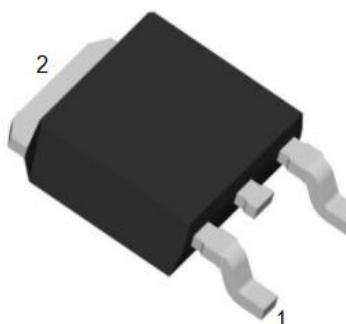
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

■ Features

- Low $R_{DS(ON)}$
- Ultra Low Gate Charge
- RoHS Compliant
- 100% UIS and RG Tested

■ Product Summary

V_{DS}	430	V
I_D	11	A
$R_{DS(ON),Typ}@10V$	0.47	Ω
Q_g	20	nC



Gate: 1
Drain: 2
Source: 3

TO-252

Marking	Package	Packaging	Min. package quantity
MKIRF11N45	TO-252	Tube	1000





■ Absolute Maximum Ratings (T_c=25°C unless otherwise noted)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DS}	430	V
Gate-Source Voltage	V _{GS}	±30	V
Continuous Drain Current T _c =25°C (Note 1)	I _D	11	A
Continuous Drain Current T _c =100°C (Note 1)		6.8	
Drain Current-Pulsed (Note 1)	I _{DM}	44	A
Total Dissipation	P _D	90	W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	E _{AS}	450	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

■ Thermal Characteristics

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R _{θJC}	1.39	°C/W
Maximum Junction-to-Ambient	R _{θJA}	60	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD}=50V, T_{ch}= 25°C(initial), I_{AS}=11A, R_g=25Ω.

Note 3: The value of R_{θJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The value in any given application depends on the user's specific board design.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





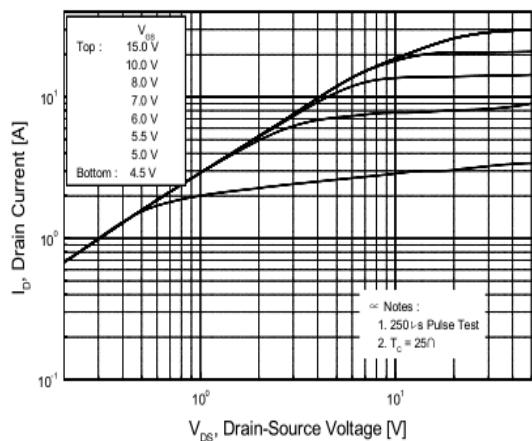
■ Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static Parameters						
Drain-Source Breakdown Voltage	B _{V_{DSS}}	V _{GS} =0V, I _D =250uA	430	-	-	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =430V, V _{GS} =0V	-	-	1	uA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	2	3	4	V
Drain-Source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5.5A	-	0.47	0.5	Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	1120	-	pF
Output Capacitance	C _{oss}		-	118	-	pF
Reverse Transfer Capacitance	C _{rss}		-	10	-	pF
Gate Resistance	R _g	V _{DS} =0V, V _{GS} =0V, f=1.0MHz	-	2	-	Ω
Switching Paramters						
Turn-On Delay Time	t _{d(on)}	V _{DS} =250V, I _D =11A, V _{GS} =10V, R _G =25Ω	-	32	-	ns
Turn-On Rise Time	t _r		-	28	-	ns
Turn-Off Delay Time	t _{d(off)}		-	90	-	ns
Turn-Off Fall Time	t _f		-	50	-	ns
Total Gate Charge	Q _g	V _{DS} =320V, I _D =11A, V _{GS} =10V	-	20	-	nC
Gate-Source Charge	Q _{gs}		-	6.5	-	nC
Gate-Drain Charge	Q _{gd}		-	4.5	-	nC
Source-Drain Characteristics						
Max. Diode Forward Cuurent	I _S		-	-	11	A
Max. Pulsed Forward Cuurent	I _{SM}		-	-	44	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =11A	-	0.86	1.5	V
Reverse Recovery Time	t _{rr}	V _R =320V, I _F =11A, di/dt=100A/us	-	320	-	ns
Reverse Recovery Charge	Q _{rr}		-	3.2	-	μC

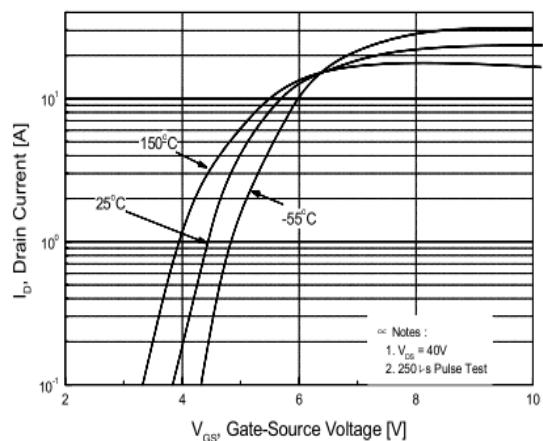




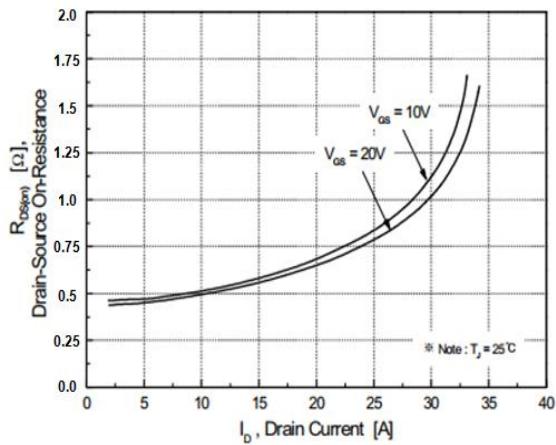
■ Characteristics Curves



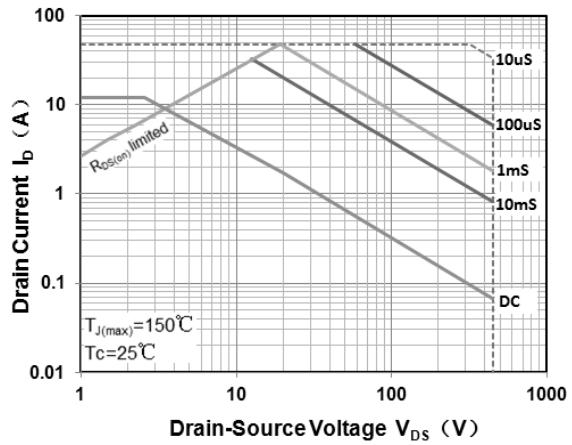
Output Characteristics



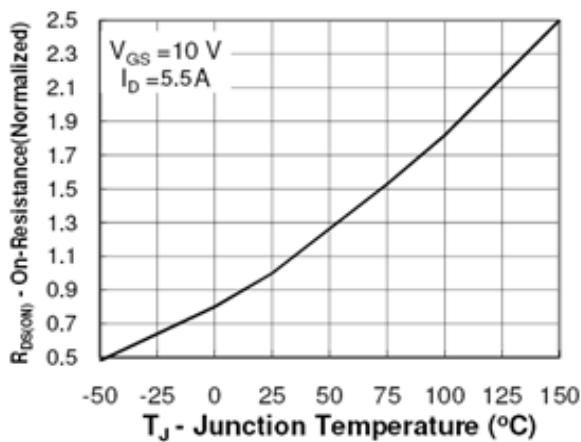
Transfer Characteristics



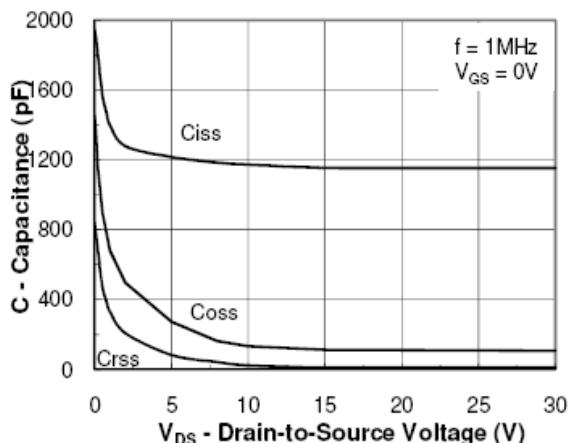
On Resistance Vs Drain Current



Safe Operating Area



Rdson-JunctionTemperature



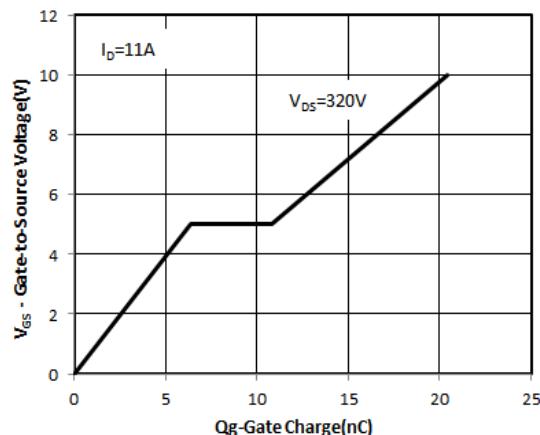
Capacitance



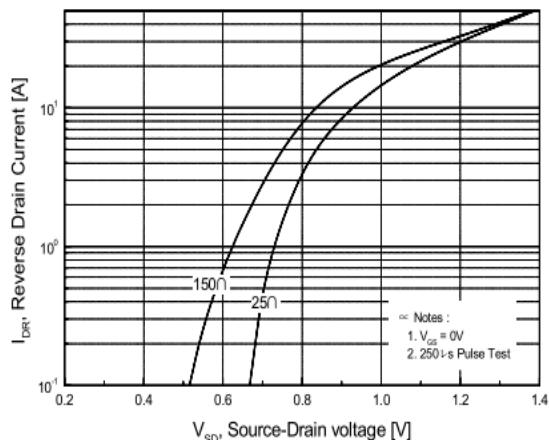


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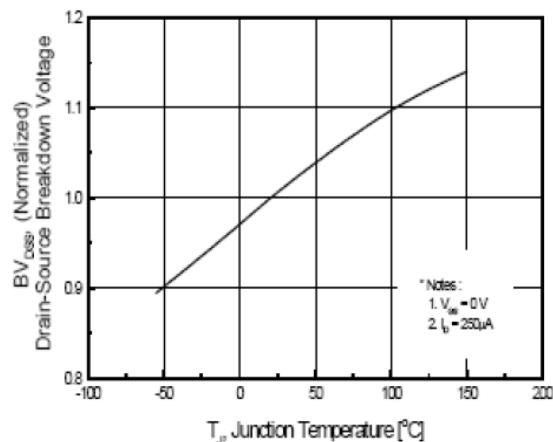
MKIRF11N45



Gate Charge Waveform



Source-Drain Diode Forward Voltage



Breakdown Voltage Vs Junction Temperature

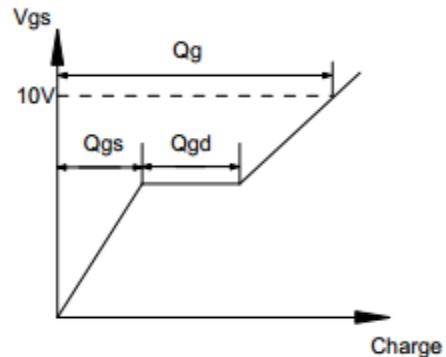
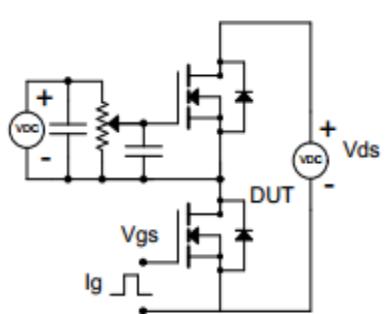
Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



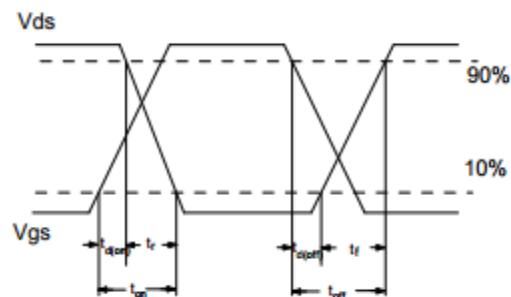
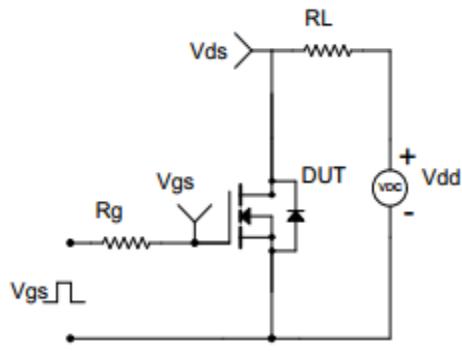


■ Test Circuit & Waveform

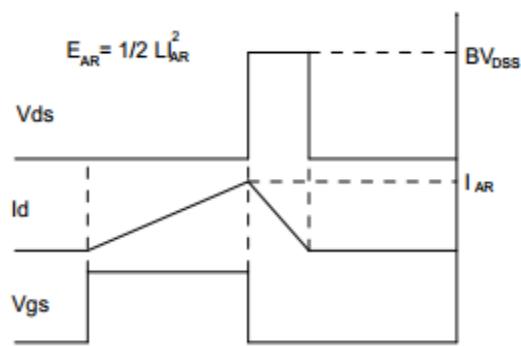
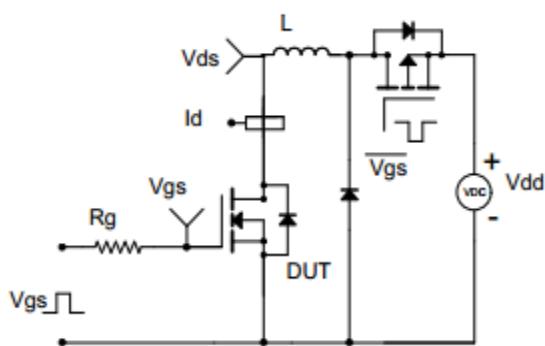
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveform





■ TO-252 Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	2.10		2.50	E	5.80		6.30
B	0.80		1.25	e1	2.25	2.30	2.35
b	0.50		0.85	e2	4.45		4.75
b1	0.50		0.90	L1	9.50		10.20
b2	0.45		0.60	L2	0.90		1.45
C	0.45		0.60	L3	0.60		1.10
D	6.35		6.75	K	-0.1		0.10
D1	5.10		5.50				

